



Ultra Series™ Crystal Oscillator

Si562 Data Sheet

Ultra Low Jitter Quad Any-Frequency XO (90 fs), 0.2 to 3000 MHz

The Si562 Ultra Series™ oscillator utilizes Silicon Laboratories' advanced 4th generation DSPLL® technology to provide an ultra-low jitter, low phase noise clock at four selectable frequencies. The device is factory-programmed to provide any four selectable frequencies from 0.2 to 3000 MHz with <1 ppb resolution and maintains exceptionally low jitter for both integer and fractional frequencies across its operating range. The Si562 offers excellent reliability and frequency stability as well as guaranteed aging performance. On-chip power supply filtering provides industry-leading power supply noise rejection, simplifying the task of generating low jitter clocks in noisy systems that use switched-mode power supplies. Offered in industry-standard footprints, the Si562 has a dramatically simplified supply chain that enables Silicon Labs to ship custom frequency samples 1-2 weeks after receipt of order. Unlike a traditional XO, where a different crystal is required for each output frequency, the Si562 uses one simple crystal and a DSPLL IC-based approach to provide the desired output frequencies. This process also guarantees 100% electrical testing of every device. The Si562 is factory-configurable for a wide variety of user specifications, including frequency, output format, and OE pin location/polarity. Specific configurations are factory-programmed at time of shipment, eliminating the long lead times associated with custom oscillators.

KEY FEATURES

- Available with any four selectable frequencies from 200 kHz to 3000 MHz
- Ultra low jitter: 90 fs RMS typical (12 kHz – 20 MHz)
- Excellent PSNR and supply noise immunity: -80 dBc Typ
- 20 ppm temp stability (-40 to 85 °C)
- 3.3 V, 2.5 V and 1.8 V V_{DD} supply operation from the same part number
- LVPECL, LVDS, CML, HCSL, CMOS, and Dual CMOS output options
- 2.5x3.2, 3.2x5, 5x7 mm package options
- Samples available with 1-2 week lead times

APPLICATIONS

- 100G/200G/400G OTN, coherent optics
- 10G/25G/40G/100G Ethernet
- 3G-SDI/12G-SDI/24G-SDI broadcast video
- Servers, switches, storage, NICs, search acceleration
- Test and measurement
- Clock and data recovery
- FPGA/ASIC clocking

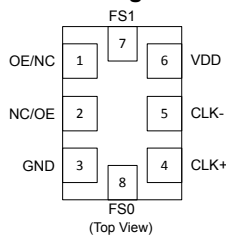


5 x 7 mm and 3.2 x 5 mm

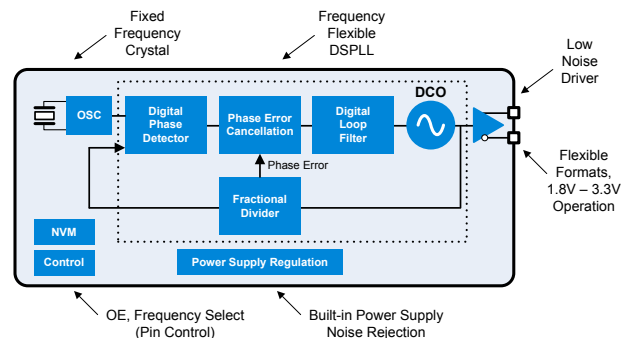


2.5 x 3.2 mm

Pin Assignments

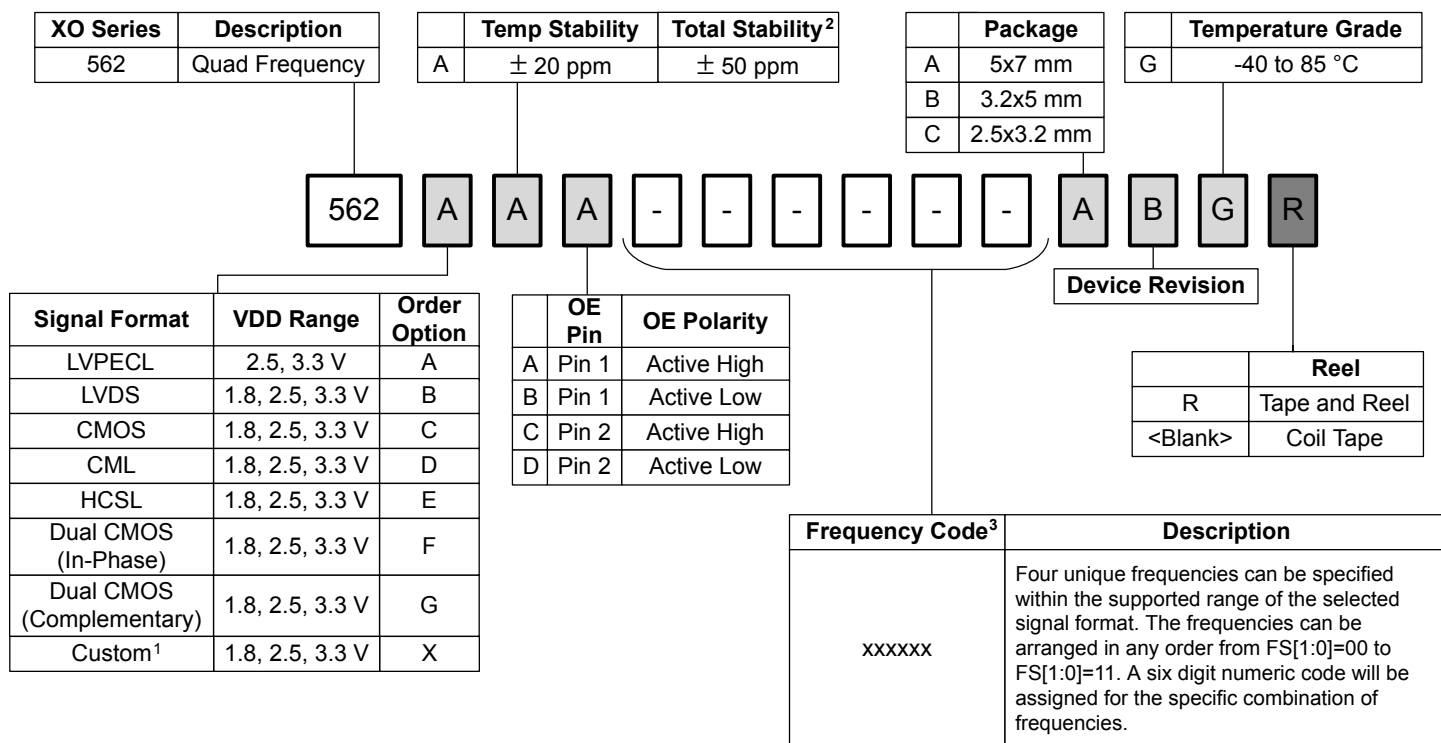


Pin #	Descriptions
1, 2	Selectable via ordering option OE = Output enable; NC = No Connect
3	GND = Ground
4	CLK+ = Clock output
5	CLK- = Complementary clock output. Not used for CMOS.
6	VDD = Power supply
7	FS1 = Frequency Select 1
8	FS0 = Frequency Select 0



1. Ordering Guide

The Si562 XO supports a variety of options including frequency, output format, and OE pin location/polarity, as shown in the chart below. Specific device configurations are programmed into the part at time of shipment, and samples are available in 1-2 weeks. Silicon Laboratories provides an online part number configuration utility to simplify this process. Refer to www.silabs.com/oscillators to access this tool and for further ordering instructions.



Notes:

- Contact Silicon Labs for non-standard configurations.
- Total stability includes temp stability, initial accuracy, load pulling, VDD variation, and 20 year aging at 70 °C.
- Create custom part numbers at www.silabs.com/oscillators.

1.1 Technical Support

Frequently Asked Questions (FAQ)	www.silabs.com/Si562-FAQ
Oscillator Phase Noise Lookup Utility	www.silabs.com/oscillator-phase-noise-lookup
Quality and Reliability	www.silabs.com/quality
Development Kits	www.silabs.com/oscillator-tools

2. Electrical Specifications

Table 2.1. Electrical Specifications
 $V_{DD} = 1.8\text{ V}, 2.5\text{ or }3.3\text{ V} \pm 5\%$, $T_A = -40\text{ to }85\text{ }^\circ\text{C}$

Parameter	Symbol	Test Condition/Comment	Min	Typ	Max	Unit
Temperature Range	T_A		-40	—	85	$^\circ\text{C}$
Frequency Range	F_{CLK}	LVPECL, LVDS, CML	0.2	—	3000	MHz
		HCSL	0.2	—	400	MHz
		CMOS, Dual CMOS	0.2	—	250	MHz
Supply Voltage	V_{DD}	3.3 V	3.135	3.3	3.465	V
		2.5 V	2.375	2.5	2.625	V
		1.8 V	1.71	1.8	1.89	V
Supply Current	I_{DD}	LVPECL (output enabled)	—	110	160	mA
		LVDS/CML (output enabled)	—	90	130	mA
		HCSL (output enabled)	—	85	130	mA
		CMOS (output enabled)	—	85	135	mA
		Dual CMOS (output enabled)	—	95	145	mA
		Tristate Hi-Z (output disabled)	—	73	—	mA
Temperature Stability		Frequency stability Grade A	-20	—	20	ppm
Total Stability ¹	F_{STAB}	Frequency stability Grade A	-50	—	50	ppm
Rise/Fall Time (20% to 80% V_{PP})	T_R/T_F	LVPECL/LVDS/CML	—	—	350	ps
		CMOS / Dual CMOS ($C_L = 5\text{ pF}$)	—	0.5	1.5	ns
		HCSL, $F_{CLK} > 50\text{ MHz}$	—	—	550	ps
Duty Cycle	D_C	All formats	45	—	55	%
Output Enable (OE) Frequency Select (FS0, FS1) ²	V_{IH}		$0.7 \times V_{DD}$	—	—	V
	V_{IL}		—	—	$0.3 \times V_{DD}$	V
	T_D	Output Disable Time, $F_{CLK} > 10\text{ MHz}$	—	—	3	μs
	T_E	Output Enable Time, $F_{CLK} > 10\text{ MHz}$	—	—	20	μs
	T_{FS}	Settling Time after FS Change	—	—	10	ms
Powerup Time	t_{OSC}	Time from $0.9 \times V_{DD}$ until output frequency (F_{CLK}) within spec	—	—	10	ms
Powerup VDD Ramp Rate	V_{RAMP}	Fastest V_{DD} ramp rate allowed on startup	—	—	9	V/ms
LVPECL Output Option ³	V_{OC}	Mid-level	$V_{DD} - 1.42$	—	$V_{DD} - 1.25$	V
	V_O	Swing (diff, $F_{CLK} \leq 1.5\text{ GHz}$)	1.1	—	1.9	V_{PP}
		Swing (diff, $F_{CLK} > 1.5\text{ GHz}$) ⁶	0.55	—	1.7	V_{PP}

Parameter	Symbol	Test Condition/Comment	Min	Typ	Max	Unit
LVDS Output Option ⁴	V _{OC}	Mid-level (2.5 V, 3.3 V V _{DD})	1.125	1.20	1.275	V
		Mid-level (1.8 V V _{DD})	0.8	0.9	1.0	V
	V _O	Swing (diff, F _{CLK} ≤ 1.4 GHz)	0.6	0.7	0.9	V _{PP}
		Swing (diff, F _{CLK} > 1.4 GHz) ⁶	0.25	0.5	0.8	V _{PP}
HCSL Output Option ⁵	V _{OH}	Output voltage high	660	800	850	mV
	V _{OL}	Output voltage low	-150	0	150	mV
	V _C	Crossing voltage	250	410	550	mV
CML Output Option (AC-Coupled)	V _O	Swing (diff, F _{CLK} ≤ 1.5 GHz)	0.6	0.8	1.0	V _{PP}
		Swing (diff, F _{CLK} > 1.5 GHz) ⁶	0.3	0.55	0.9	V _{PP}
CMOS Output Option	V _{OH}	I _{OH} = 8/6/4 mA for 3.3/2.5/1.8 V V _{DD}	0.85 × V _{DD}	—	—	V
	V _{OL}	I _{OL} = 8/6/4 mA for 3.3/2.5/1.8 V V _{DD}	—	—	0.15 × V _{DD}	V

Notes:

- Total Stability includes temperature stability, initial accuracy, load pulling, V_{DD} variation, and aging for 20 yrs at 70 °C.
- OE includes a 50 kΩ pull-up to V_{DD} for OE active high, or includes a 50 kΩ pull-down to GND for OE active low. FS0 and FS1 pins each include a 50 kΩ pull-up to V_{DD}. NC (No Connect) pins include a 50 kΩ pull-down to GND.
- R_{term} = 50 Ω to V_{DD} - 2.0 V (see Figure 4.1).
- R_{term} = 100 Ω (differential) (see Figure 4.2).
- R_{term} = 50 Ω to GND (see Figure 4.2).
- Refer to the figure below for Typical Clock Output Swing Amplitudes vs Frequency.

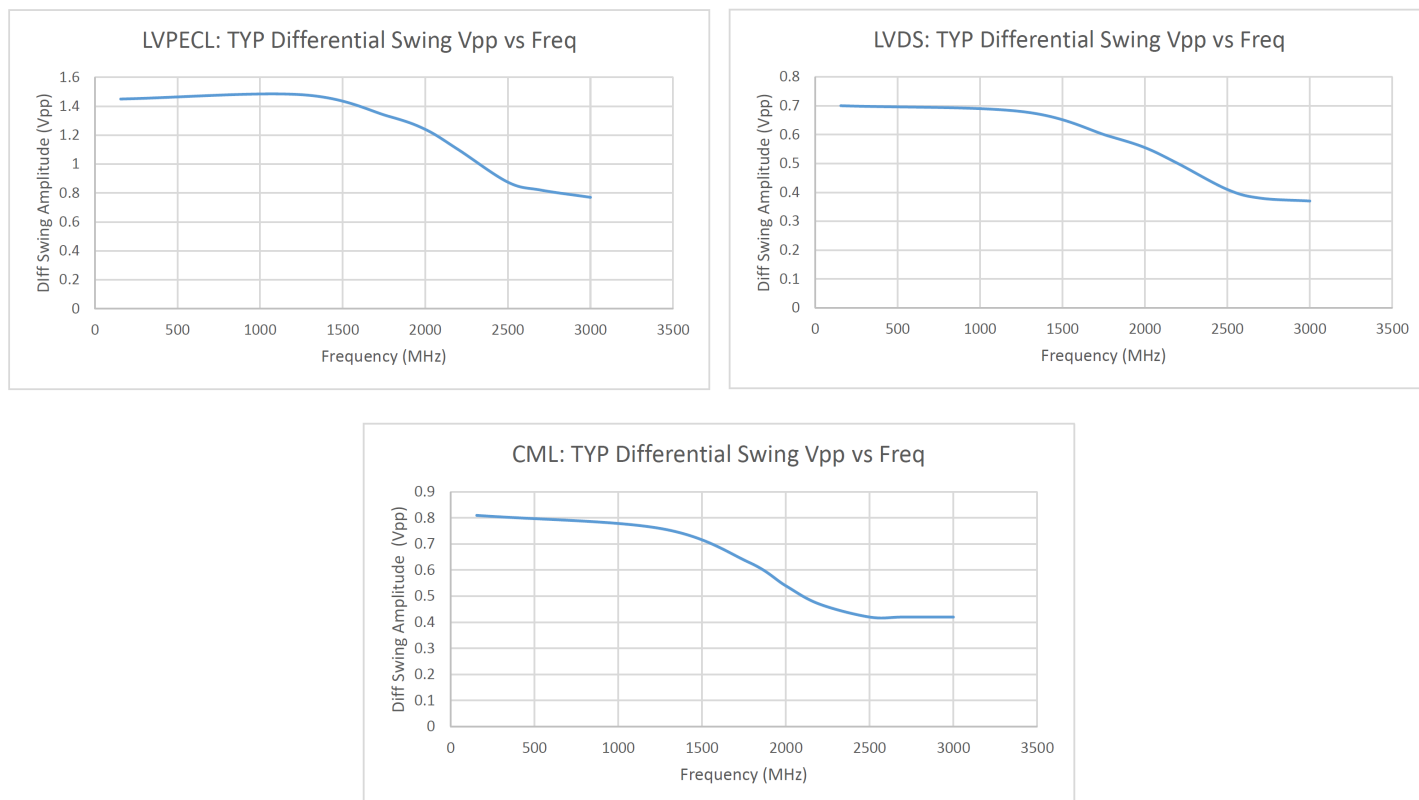
**Figure 2.1. Typical Clock Output Swing Amplitudes vs. Frequency**

Table 2.2. Clock Output Phase Jitter and PSNR

$V_{DD} = 1.8\text{ V}, 2.5\text{ or }3.3\text{ V} \pm 5\%$, $T_A = -40\text{ to }85\text{ }^\circ\text{C}$

Parameter	Symbol	Test Condition/Comment	Min	Typ	Max	Unit
Phase Jitter (RMS, 12 kHz - 20 MHz) ¹ All Differential Formats	ϕ_J	$F_{CLK} \geq 200\text{ MHz}$	—	90	140	fs
		$100\text{ MHz} \leq F_{CLK} < 200\text{ MHz}$	—	105	160	fs
		LVPECL @ 156.25 MHz	—	95	135	fs
Phase Jitter (RMS, 12 kHz - 20 MHz) ¹ CMOS / Dual CMOS Formats	ϕ_J	$10\text{ MHz} \leq F_{CLK} < 250\text{ MHz}$	—	200	—	fs
Spurs Induced by External Power Supply Noise, 50 mVpp Ripple. LVDS 156.25 MHz Output	PSNR	100 kHz sine wave		-83		dBc
		200 kHz sine wave		-83		
		500 kHz sine wave		-82		
		1 MHz sine wave		-85		

Note:

1. Guaranteed by characterization. Jitter inclusive of any spurs.

Table 2.3. 3.2 x 5 mm Clock Output Phase Noise (Typical)

Offset Frequency (f)	156.25 MHz LVDS	200 MHz LVDS	644.53125 MHz LVDS	Unit
100 Hz	-105	-100	-92	dBc/Hz
1 kHz	-129	-126	-116	
10 kHz	-136	-133	-125	
100 kHz	-142	-140	-131	
1 MHz	-150	-148	-138	
10 MHz	-159	-161	-153	
20 MHz	-160	-162	-154	
Offset Frequency (f)	156.25 MHz LVPECL	200 MHz LVPECL	644.53125 MHz LVPECL	Unit
100 Hz	-109	-102	-92	dBc/Hz
1 kHz	-131	-126	-119	
10 kHz	-135	-134	-124	
100 kHz	-143	-141	-130	
1 MHz	-150	-148	-138	
10 MHz	-160	-162	-154	
20 MHz	-161	-163	-155	

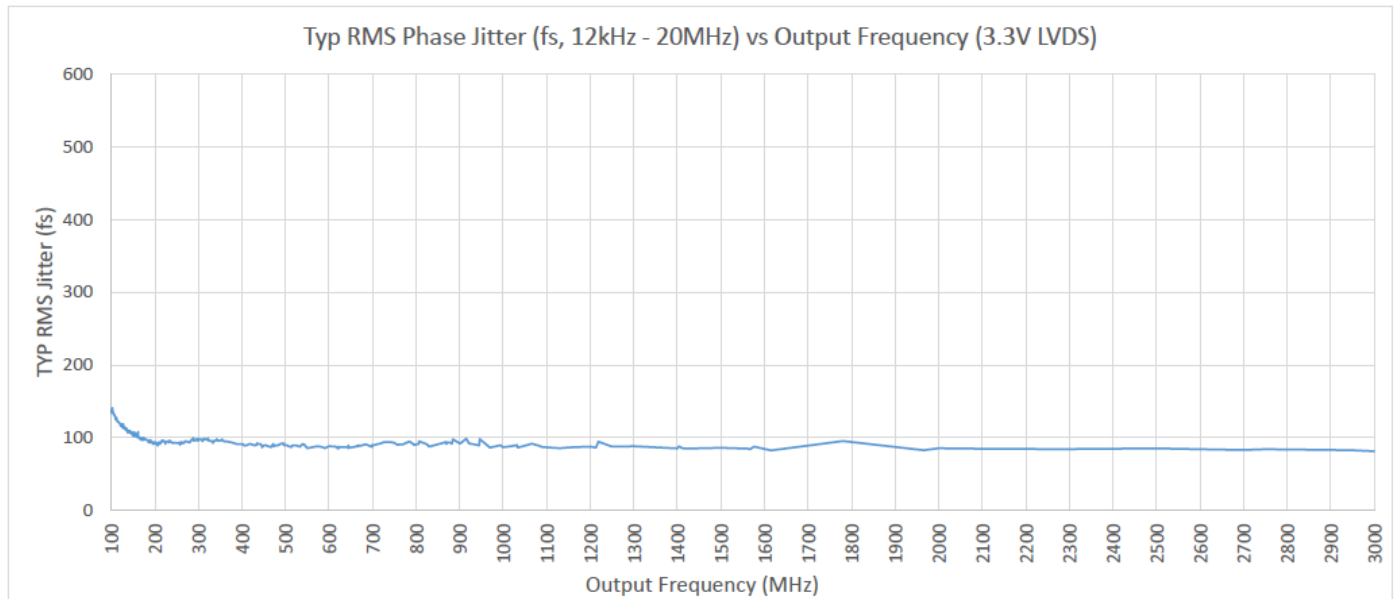


Figure 2.2. Phase Jitter vs. Output Frequency

Phase jitter measured with Agilent E5052 using a differential-to-single ended converter (balun or buffer). Measurements collected for >700 commonly used frequencies. Phase noise plots for specific frequencies are available using our free, online Oscillator Phase Noise Lookup Tool at www.silabs.com/oscillators.

Table 2.4. Environmental Compliance and Package Information

Parameter	Test Condition
Mechanical Shock	MIL-STD-883, Method 2002
Mechanical Vibration	MIL-STD-883, Method 2007
Solderability	MIL-STD-883, Method 2003
Gross and Fine Leak	MIL-STD-883, Method 1014
Resistance to Solder Heat	MIL-STD-883, Method 2036
Moisture Sensitivity Level (MSL): 3.2 x 5, 5 x 7 packages	1
Moisture Sensitivity Level (MSL): 2.5 x 3.2 package	2
Contact Pads: 3.2x5, 5x7 packages	Au/Ni (0.3 - 1.0 μm / 1.27 - 8.89 μm)
Contact Pads: 2.5x3.2 packages	Au/Pd/Ni (0.03 - 0.12 μm / 0.1 - 0.2 μm / 3.0 - 8.0 μm)
Note:	
1. For additional product information not listed in the data sheet (e.g. RoHS Certifications, MDDS data, qualification data, REACH Declarations, ECCN codes, etc.), refer to our "Corporate Request For Information" portal found here: www.silabs.com/support/quality/Pages/RoHSInformation.aspx .	

Table 2.5. Thermal Conditions¹

Max Junction Temperature = 125° C

Package	Parameter	Symbol	Test Condition	Value	Unit
2.5 x 3.2 mm 8-pin DFN ²	Thermal Resistance Junction to Ambient	Θ_{JA}	Still Air, 85 °C	72	°C/W
	Thermal Parameter Junction to Board	Ψ_{JB}	Still Air, 85 °C	38	°C/W
	Thermal Parameter Junction to Top Center	Ψ_{JT}	Still Air, 85 °C	15	°C/W
3.2 x 5 mm 8-pin CLCC	Thermal Resistance Junction to Ambient	Θ_{JA}	Still Air, 85 °C	55	°C/W
	Thermal Parameter Junction to Board	Ψ_{JB}	Still Air, 85 °C	20	°C/W
	Thermal Parameter Junction to Top Center	Ψ_{JT}	Still Air, 85 °C	20	°C/W
5 x 7 mm 8-pin CLCC	Thermal Resistance Junction to Ambient	Θ_{JA}	Still Air, 85 °C	53	°C/W
	Thermal Parameter Junction to Board	Ψ_{JB}	Still Air, 85 °C	26	°C/W
	Thermal Parameter Junction to Top Center	Ψ_{JT}	Still Air, 85 °C	26	°C/W
Note:					
1. Based on PCB Dimensions: 4.5" x 7", PCB Thickness: 1.6 mm, Number of Cu Layers: 4.					
2. For best 2.5x3.2mm thermal performance, use 2 GND vias as shown in the Si5xxUC-EVB eval board layout					

Table 2.6. Absolute Maximum Ratings¹

Parameter	Symbol	Rating	Unit
Maximum Operating Temp.	T_{AMAX}	95	°C
Storage Temperature	T_S	-55 to 125	°C
Supply Voltage	V_{DD}	-0.5 to 3.8	°C
Input Voltage	V_{IN}	-0.5 to $V_{DD} + 0.3$	V
ESD HBM (JESD22-A114)	HBM	2.0	kV
Solder Temperature ²	T_{PEAK}	260	°C
Solder Time at T_{PEAK} ²	T_P	20–40	sec

Notes:

1. Stresses beyond those listed in this table may cause permanent damage to the device. Functional operation specification compliance is not implied at these conditions. Exposure to maximum rating conditions for extended periods may affect device reliability.
2. The device is compliant with JEDEC J-STD-020.

3. Dual CMOS Buffer

Dual CMOS output format ordering options support either complementary or in-phase signals for two identical frequency outputs. This feature enables replacement of multiple XOs with a single Si562 device.

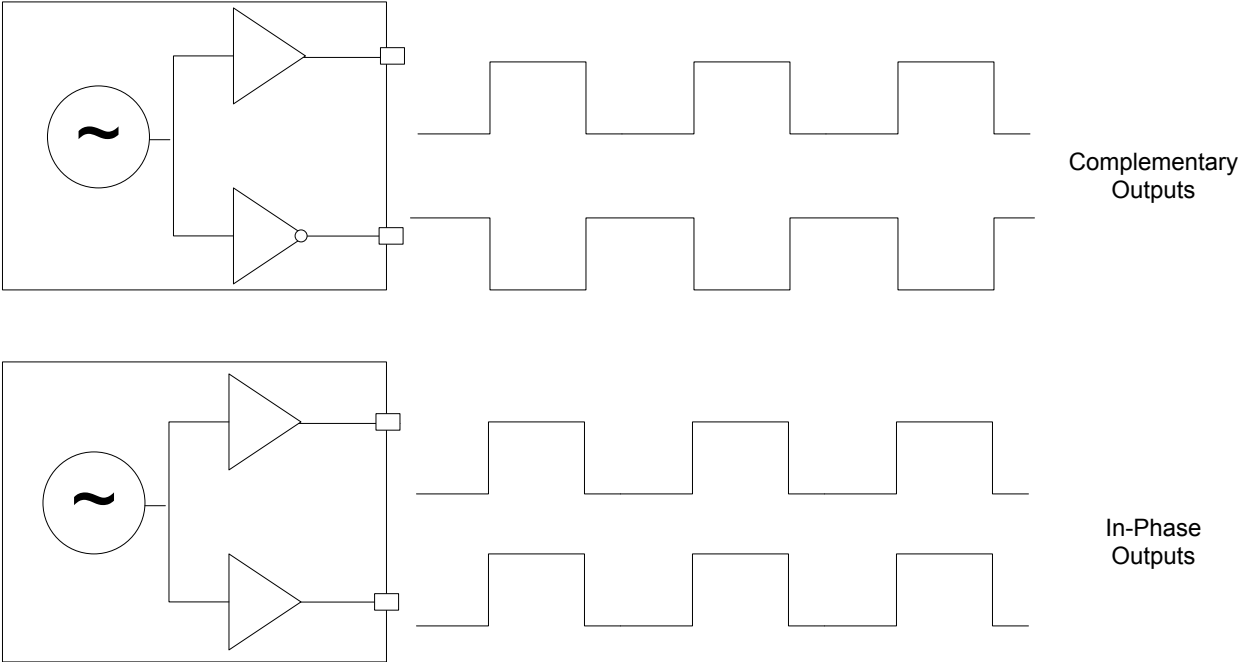


Figure 3.1. Integrated 1:2 CMOS Buffer Supports Complementary or In-Phase Outputs

4. Recommended Output Terminations

The output drivers support both AC-coupled and DC-coupled terminations as shown in figures below.

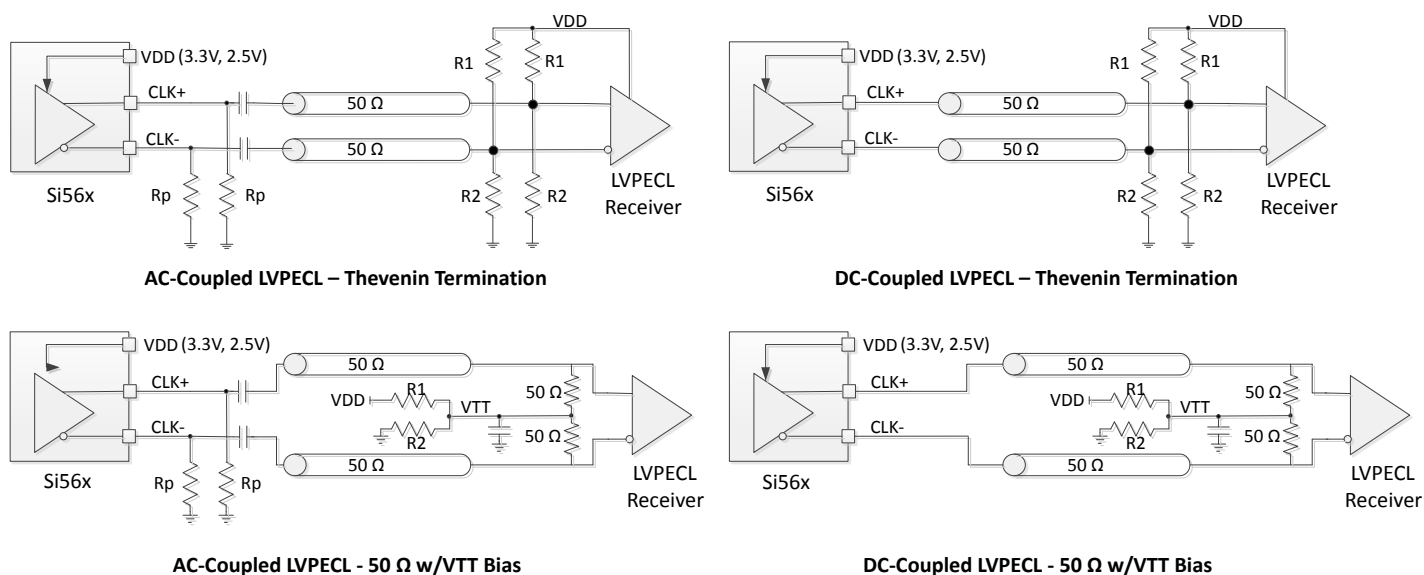


Figure 4.1. LVPECL Output Terminations

AC-Coupled LVPECL Termination Resistor Values				DC-Coupled LVPECL Termination Resistor Values		
VDD	R1	R2	Rp	VDD	R1	R2
3.3 V	127 Ω	82.5 Ω	130 Ω	3.3 V	127 Ω	82.5 Ω
2.5 V	250 Ω	62.5 Ω	90 Ω	2.5 V	250 Ω	62.5 Ω

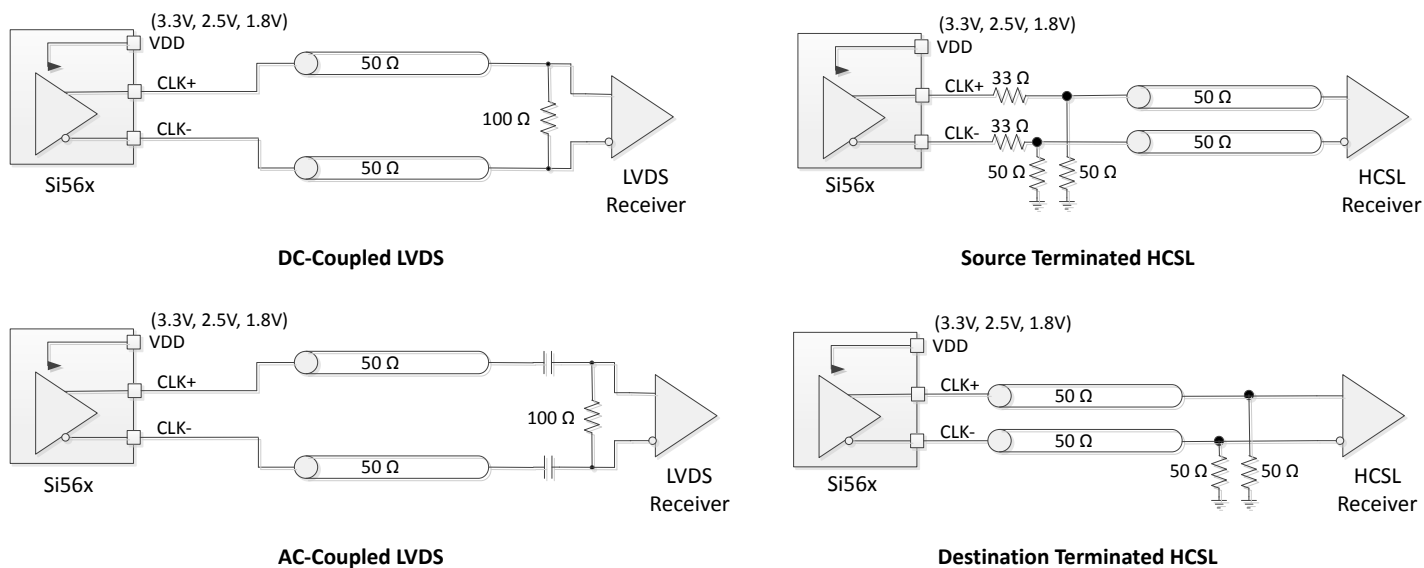


Figure 4.2. LVDS and HCSL Output Terminations

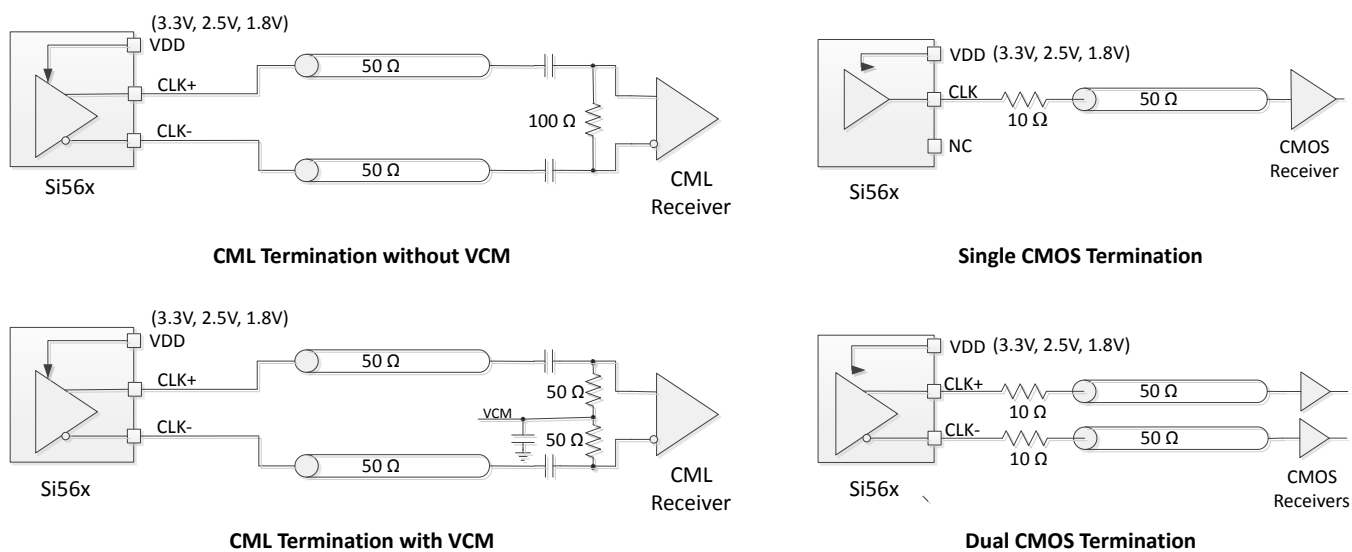


Figure 4.3. CML and CMOS Output Terminations

5. Package Outline

5.1 Package Outline (5x7 mm)

The figure below illustrates the package details for the 5x7 mm Si562. The table below lists the values for the dimensions shown in the illustration.

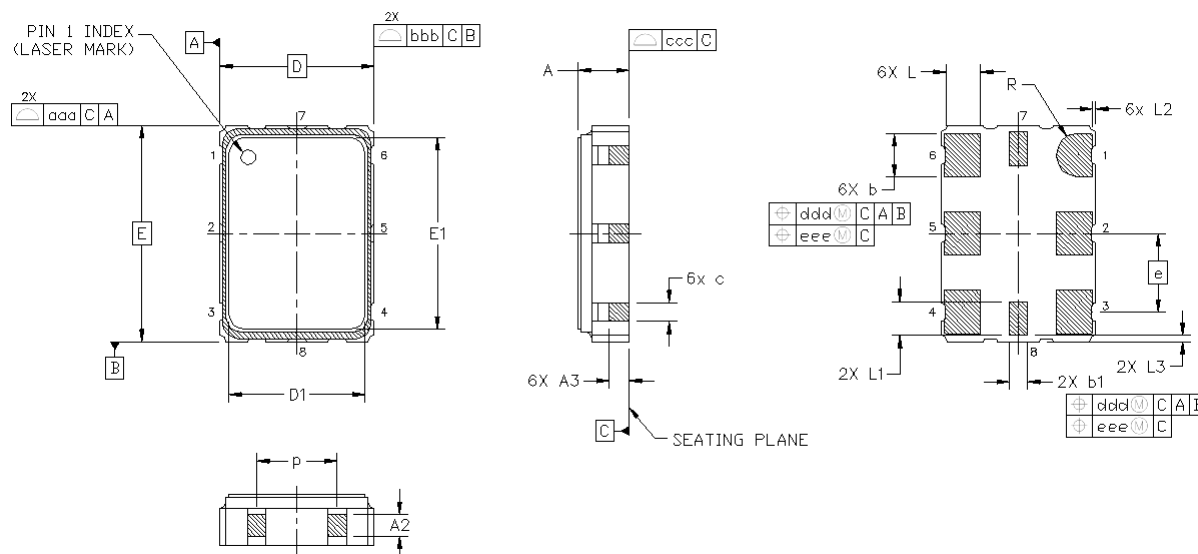


Figure 5.1. Si562 (5x7 mm) Outline Diagram

Table 5.1. Package Diagram Dimensions (mm)

Dimension	Min	Nom	Max	Dimension	Min	Nom	Max
A	1.07	1.18	1.33	L	1.07	1.17	1.27
A2	0.40	0.50	0.60	L1	1.00	1.10	1.20
A3	0.45	0.55	0.65	L2	0.05	0.10	0.15
b	1.30	1.40	1.50	L3	0.15	0.20	0.25
b1	0.50	0.60	0.70	p	1.70	--	1.90
c	0.50	0.60	0.70	R	0.70 REF		
D	5.00 BSC			aaa	0.15		
D1	4.30	4.40	4.50	bbb	0.15		
e	2.54 BSC			ccc	0.08		
E	7.00 BSC			ddd	0.10		
E1	6.10	6.20	6.30	eee	0.05		

Notes:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.

5.2 Package Outline (3.2x5 mm)

The figure below illustrates the package details for the 3.2x5 mm Si562. The table below lists the values for the dimensions shown in the illustration.



Figure 5.2. Si562 (3.2x5 mm) Outline Diagram

Table 5.2. Package Diagram Dimensions (mm)

Dimension	MIN	NOM	MAX	Dimension	MIN	NOM	MAX
A	1.02	1.17	1.33	E1	2.85 BSC		
A2	0.50	0.55	0.60	L	0.8	0.9	1.0
A3	0.45	0.50	0.55	L1	0.45	0.55	0.65
b	0.54	0.64	0.74	L2	0.05	0.10	0.15
b1	0.54	0.64	0.75	L3	0.15	0.20	0.25
D	5.00 BSC			aaa	0.15		
D1	4.65 BSC			bbb	0.15		
e	1.27 BSC			ccc	0.08		
e1	1.625 TYP			ddd	0.10		
E	3.20 BSC			eee	0.05		

Notes:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.

5.3 Package Outline (2.5x3.2 mm)

The figure below illustrates the package details for the 2.5x3.2 mm Si562. The table below lists the values for the dimensions shown in the illustration.

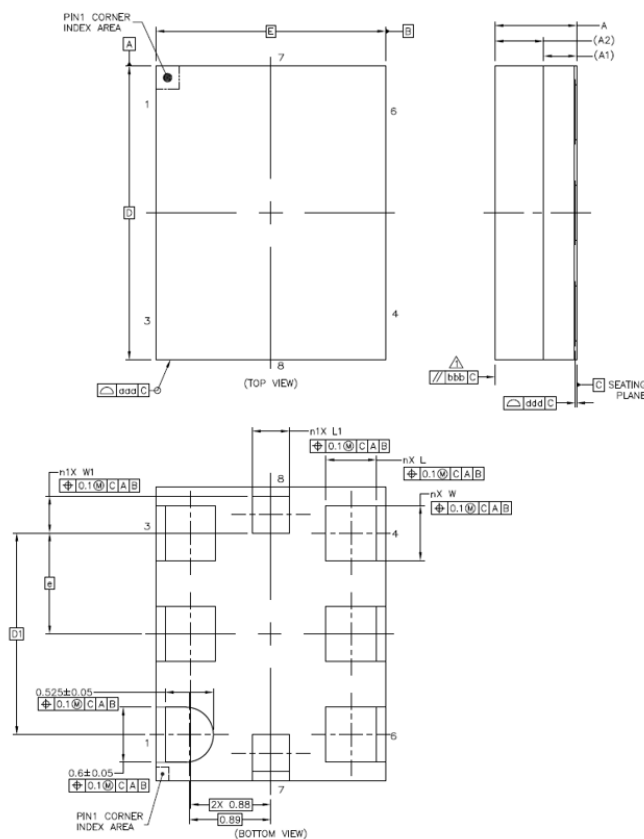


Figure 5.3. Si562 (2.5x3.2 mm) Outline Diagram

Table 5.3. Package Diagram Dimensions (mm)

Dimension	MIN	NOM	MAX	Dimension	MIN	NOM	MAX
A	—	—	1	L1	0.35	0.4	0.45
A1	0.36 REF			e	1.1 BSC		
A2	0.53 REF			n	5		
D	3.2 BSC			n1	2		
E	2.5 BSC			D1	2.2 BSC		
W	0.55	0.6	0.65	aaa	0.10		
L	0.5	0.55	0.6	bbb	0.10		
W1	0.35	0.4	0.45	ddd	0.08		

Notes:

1. The dimensions in parentheses are reference.
2. All dimensions shown are in millimeters (mm) unless otherwise noted.
3. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

6. PCB Land Pattern

6.1 PCB Land Pattern (5x7 mm)

The figure below illustrates the 5x7 mm PCB land pattern for the Si562. The table below lists the values for the dimensions shown in the illustration.



Figure 6.1. Si562 (5x7 mm) PCB Land Pattern

Table 6.1. PCB Land Pattern Dimensions (mm)

Dimension	(mm)	Dimension	(mm)
C1	4.20	Y1	1.95
C2	6.05	X2	1.80
E	2.54	Y2	0.75
X1	1.55		

Notes:

General

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification.
3. This Land Pattern Design is based on the IPC-7351 guidelines.
4. All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.

Solder Mask Design

1. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 μm minimum, all the way around the pad.

Stencil Design

1. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
2. The stencil thickness should be 0.125 mm (5 mils).
3. The ratio of stencil aperture to land pad size should be 1:1.

Card Assembly

1. A No-Clean, Type-3 solder paste is recommended.
2. The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

6.2 PCB Land Pattern (3.2x5 mm)

The figure below illustrates the 3.2x5.0 mm PCB land pattern for the Si562. The table below lists the values for the dimensions shown in the illustration.



Figure 6.2. Si562 (3.2x5 mm) PCB Land Pattern

Table 6.2. PCB Land Pattern Dimensions (mm)

Dimension	(mm)	Dimension	(mm)
C1	2.70	X2	0.90
E	1.27	Y1	1.60
E1	4.30	Y2	0.70
X1	0.74		

Notes:

General

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification.
3. This Land Pattern Design is based on the IPC-7351 guidelines.
4. All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.

Solder Mask Design

1. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 μm minimum, all the way around the pad.

Stencil Design

1. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
2. The stencil thickness should be 0.125 mm (5 mils).
3. The ratio of stencil aperture to land pad size should be 1:1.

Card Assembly

1. A No-Clean, Type-3 solder paste is recommended.
2. The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

6.3 PCB Land Pattern (2.5x3.2 mm)

The figure below illustrates the 2.5x3.2 mm PCB land pattern for the Si562. The table below lists the values for the dimensions shown in the illustration.

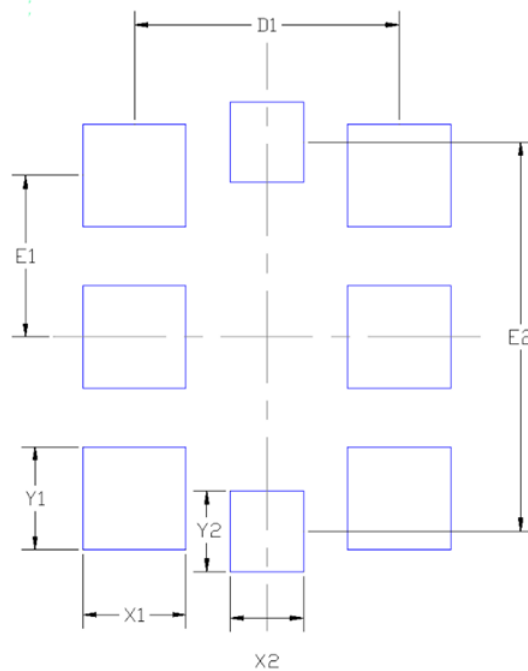


Figure 6.3. Si562 (2.5x3.2 mm) PCB Land Pattern

Table 6.3. PCB Land Pattern Dimensions (mm)

Dimension	Description	Value (mm)
X1	Width - leads on long sides	0.7
Y1	Height - leads on long sides	0.7
X2	Width - single leads on short sides	0.5
Y2	Height - single leads on short sides	0.55
D1	Pitch in X directions of XL, Y1 leads	1.80
E1	Lead pitch X1, Y1 leads	1.10
E2	Lead pitch X2, Y2 leads	2.65

Dimension	Description	Value (mm)
<p>Notes:</p> <p>General</p> <ol style="list-style-type: none">1. All dimensions shown are in millimeters (mm) unless otherwise noted.2. Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification.3. This Land Pattern Design is based on the IPC-7351 guidelines.4. All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm. <p>Solder Mask Design</p> <ol style="list-style-type: none">1. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 μm minimum, all the way around the pad. <p>Stencil Design</p> <ol style="list-style-type: none">1. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.2. The stencil thickness should be 0.125 mm (5 mils).3. The ratio of stencil aperture to land pad size should be 0.8:1 for the pads. <p>Card Assembly</p> <ol style="list-style-type: none">1. A No-Clean, Type-3 solder paste is recommended.2. The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.		

7. Top Marking (5x7 and 3.2x5 Packages)

The figure below illustrates the mark specification for the Si562 5x7 and 3.2x5 package sizes. The table below lists the line information.

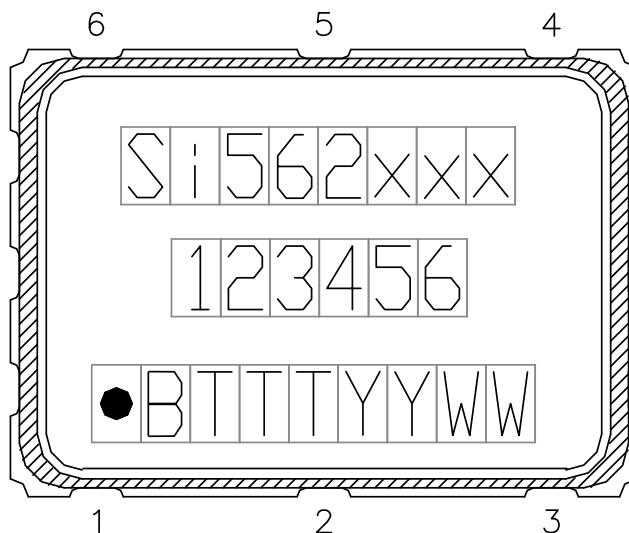


Figure 7.1. Mark Specification

Table 7.1. Si562 Top Mark Description

Line	Position	Description
1	1–8	"Si562", xxx = Ordering Option 1, Option 2, Option 3 (e.g. Si562AAA)
2	1–6	Frequency Code (6-digit custom code as described in the Ordering Guide)
3	Trace Code	
	Position 1	Pin 1 orientation mark (dot)
	Position 2	Product Revision (B)
	Position 3–5	Tiny Trace Code (3 alphanumeric characters per assembly release instructions)
	Position 6–7	Year (last two digits of the year), to be assigned by assembly site (ex: 2017 = 17)
	Position 8–9	Calendar Work Week number (1–53), to be assigned by assembly site

8. Top Marking (2.5x3.2 Package)

The figure below illustrates the mark specification for the Si562 2.5x3.2 package sizes. The table below lists the line information.

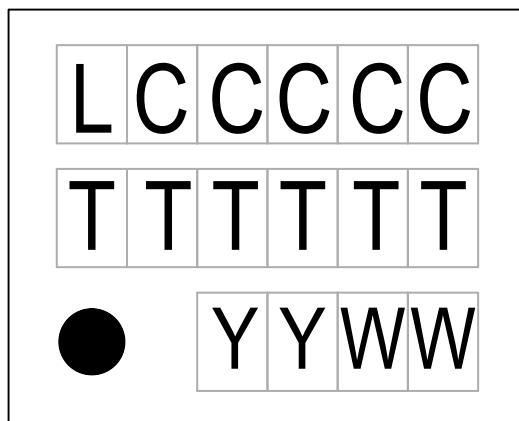


Figure 8.1. Mark Specification

Table 8.1. Si562 Top Mark Description

Line	Position	Description
1	1–6	L = Si562, CCCCC = Custom Mark Code
2	Trace Code	
	1–6	Six-digit trace code per assembly release instructions
3	Position 1	Pin 1 orientation mark (dot)
	Position 2–3	Year (last two digits of the year), to be assigned by assembly site (exp: 2017 = 17)
	Position 4–5	Calendar Work Week number (1–53), to be assigned by assembly site

9. Revision History

Revision 1.2

September, 2020

- Added 2.5 x 3.2 mm package option.
- Updated Table 2.2, Powerup VDD Ramp Rate and LVDS Swing.

Revision 1.0

June, 2018

- Initial release.



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